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ESD

TVS

TSS

MOV

GDT

PIFD

SN74LVC1G27DBVR-MS/SN74LVC1G27DCKR-MS

Product specification



General Description

This single 3-input positive-NOR gate is designed for 1.65-V to 5.5-VVcc operation.

The SN74LVC1G27DBVR-MS/SN74LVC1G27DCKR-MS device performs the Boolean function

 $Y=\overline{A}+\overline{B}+\overline{C}$ or $Y=\overline{A}\cdot\overline{B}\cdot\overline{C}$ in positive logic. The CMOS device has high output drive while maintaining low static power dissipation over a broad V_{CC} operating range.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry prevents damaging current backflow through the device when the gate is powered down and its output is floating.

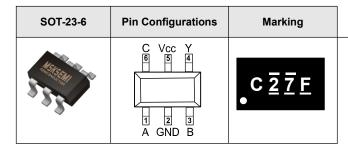
Features

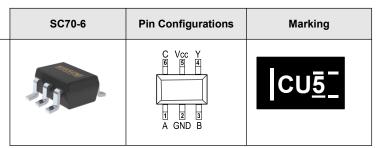
- Operate from 1.65 V to 5.5V
- Supports 5V VCC operation
- Specified from -40[°]C to 125[°]C
- Provides down translation to Vcc
- Max tpd of 5.4 ns at 3.3 V
- ±24-mA output drive at 3.3 V

Applications

- Personal digital assistant devices
- AV receiver
- MP3 player/recorder
- Solid state drive(SSD):client and enterprise
- Power:telecom/server AC/DC supply
- TV:LCD/digital and high-definition (HDTV)

Pinning and Marking





Pin Functions

Pin		I/O	Description
Name	SOT23-6/SC70-6	1/0	Description
Α	1		Data Input
GND	2	-	Ground
В	3		Data Input
Υ	4	0	Data Output
VCC	5	-	Supply Voltage
С	6		Data Input

Order information

Orderable Device	Package	Packing Option
SN74LVC1G27DBVR-MS	SOT23-6	3000PCS
SN74LVC1G27DCKR-MS	SC70-6	3000PCS



CircuitDiagram



Absolute Maximum Ratings

	Paramete	Min	Max.	Unit	
Vcc	Supply vol	age range	-0.5	6.5	V
VI	Input volta	ige range	-0.5	6.5	V
Vo	Voltage range applied to any output in the	ne high-impedance or power-off state(2)	-0.5	6.5	V
Vo	Voltage range applied to any	-0.5	V _{CC} +0.5	V	
lıĸ	Input clamp current	V < 0		-50	mA
Іок	Output clamp current	Vo<0		-50	mA
lo	Continuous o	utput current		±50	mA
	Continuous current throu	igh Vcc or GND		±100	mA
TJ	Junction tempera		150	°C	
T _{stg}	Storage temp	erature range	- 65	150	°C

⁽¹⁾ Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "Recommended Operating Conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

⁽²⁾ The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

⁽³⁾ The output positive-voltage rating may be exceeded up to 6.5 V maximum if the output current rating is observed.

Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

Symbol	Pa	arameter	Min	Max	Units	
Vcc	Supply Voltage	Operating	1.65	5.5	V	
		V _{CC} =1.65V to 1.95V	0.65×V _{CC}			
	18.1.1.11.41/16	V _{CC} =2.3V to 2.7V	1.7		.,	
V _{IH}	High-Level Input Voltage	V _{CC} =3V to 3.6V	2		V	
		V _{CC} =4.5V to 5.5V	0.7×V _{CC}		1	
		V _{CC} =1.65V to 1.95V		0.35×V _{cc}		
V	Lauri and lauri Vallana	V _{CC} =2.3V to 2.7V		0.7] ,,	
V_{IL}	Low-Level Input Voltage	V _{CC} =3V to 3.6V		0.8	V	
		V _{CC} =4.5V to 5.5V		0.3×V _{CC}	1	
Vı	In	put Vo l tage	0	5.5	٧	
Vo	Ou	ıtput Vo l tage	0	Vcc	V	
	High-Level Output Current	V _{CC} =1.65V		-4		
		V _{CC} =2.3V		-8		
I OH		V 0/		-16	m/	
		V _{CC} =3V		-24	1	
		V _{CC} =4.5V		-32	1	
		V _{CC} =1.65V		4		
		V _{CC} =2.3V		8		
l oL	Low-Level Output Current			16	m/	
		V _{CC} =3V		24	1	
		V _{CC} =4.5V		32	1	
		V _{CC} =1.8V±0.15V, 2.5V±0.2V		20		
Δt/Δν	Input Transition Rise or Fall Rate	V _{CC} =3.3V±0.3V		10	ns/V	
		V _{CC} =5V±0.5V		5		
TA	Operating Free-air Temperature	A ll Other Packages	-40	125	°C	

⁽¹⁾ All unused digital inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

Thermal Information

Package Type	0 JA	0 JC	Unit
SOT23-6	196	81	°C/W
SC70-6	178	98	°C/W



Electrical Characteristics

 V_{CC} =1.65V to 5.5V, FULL=-40°C to +125°C. Typical values are at TA=+25°C (unless otherwise noted)⁽¹⁾

Parameter	Symbol	Test Conditions	Vcc	TA	Min	Тур	Max	Units
		Output						
		I _{OH} =—100μA	1.65V to 5.5V	FULL	V _{CC} -0.1			V
		I _{OH} =—4mA	1.65V	FULL	1.2			V
		I _{OH} =—8mA	2.3V	FULL	1.9			V
Output High Voltage	V _{OH}	I _{OH} =-16mA		FULL	2.4			V
		I _{OH} =-24mA	3V	FULL	2.3			V
		I _{ОН} =—32mА	4.5V	FULL	3.8			V
		I _{OL} =100μA	1.65V to 5.5V	FULL			0.1	V
	VoL	I _{OL} =4mA	1.65V	FULL			0.45	V
		I _{OL} =8mA	2.3V	FULL			0.3	V
Output Low Voltage		I _{OL} =16mA	0.7	FULL			0.4	٧
		I _{OL} =24mA	3V	FULL			0.55	V
		I _{OL} =32mA	4.5V	FULL			0.55	V
Off-State Current	off	V₁ or V₀=5.5V	0V	FULL			±10	μA
,	-	Input	'					
Input Leakage Current	lı	V _I =5.5V or GND	0V to 5.5V	FULL			±5	μA
Input Capacitance	Cı	V _I =V _{CC} or GND	3.3V	FULL		3.5		pF
		Power Supply						
Power Supply Range	Vcc		1.65V to 5.5V	FULL	1.65		5.5	٧
Power Supply Current	Icc	V _I =V _{CC} or GND, I _O =0	5.5V	FULL			10	μA
Delta Power Current	ΔΙ _{CC}	One Input at V_{CC} – 0.6V, Other Inputs at V_{CC} or GND	3V to 5.5V	FULL			500	μΑ

⁽¹⁾ All unused digital inputs of the device must be held at V_{CC} or GND to ensure proper device operation.

Switching Characteristics

Over recommended operating free-air temperature range, C_L=30pF or 50 pF (unless otherwise noted)

		-40°C to +125°C									
Parameter	From(Input)	To(Output)	V _{cc} =1.8	V±0.15V	Vcc=2.5	5V±0.2V	V _{cc} =3.3	SV±0.3V	V _{cc} =5\	V±0.5V	Units
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{pd}	A or B or C	Y	2.2	11	1.4	8.8	1.3	5.4	1	4.7	ns

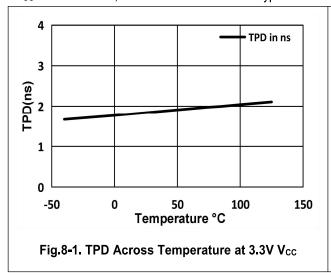
Operating Characteristics

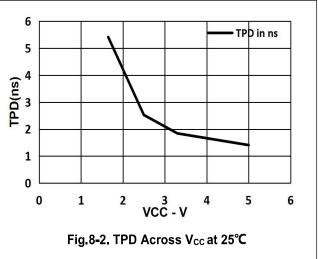
TA=-40°C to +125°C

	Parameter		Test	V _{CC} =1.8V	V _{cc} =2.5V	V _{cc} =3.3V	V _{cc} =5V	Units
			Conditions	Тур	Тур Тур		Тур	Units
	C_{pd}	Power Dissipation Capacitance	f=10Mhz	23	23	23	31	pF

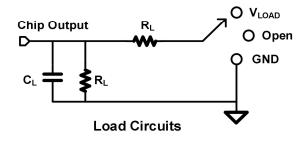
Typical Characteristics

V_{CC}=1.65V or 5.5V, FULL=-40°C to +125°C. Typical values are at TA=+25°C (unless otherwise noted)





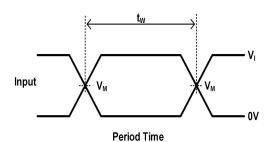
Parameter Measurement Information

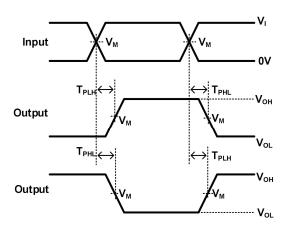


TEST	S1
T _{PHL} /T _{PLH}	OPEN
T _{PLZ} /T _{PZL}	V_{LOAD}
T _{PHZ} /T _{PZH}	GND

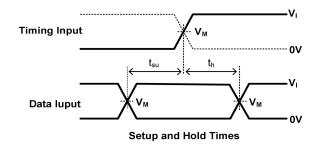
Vcc	Inputs		V _M	V _{LOAD}	CL	R∟	V_{Δ}
V CC	Vı	T _r /T _f	V M	V LOAD	OL	I I I	VΔ
1.8V±0.15V	Vcc	≤2ns	V _{CC} /2	2×V _{CC}	30pF	1kΩ	0.15V
2.5V±0.15V	Vcc	≤2ns	V _{CC} /2	2×V _{CC}	30pF	500Ω	0.15V
3.3V±0.15V	3V	≤2.5ns	1.5V	6V	50pF	500Ω	0.3V
5V±0.15V	V _{CC}	≤2.5ns	V _{CC} /2	2×V _{CC}	50pF	500Ω	0.3V

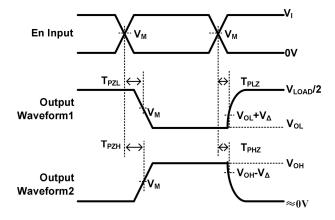
Parameter Measurement Information(Continued)





Propagation Delay for Output and Inverted Output





Enable and Disable Times Low-And High-Level Enabling

- Notes:A. C∟ includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. E. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control. G. C. All input pulses are supplied by generators having the following characteristics: PRR 10 MHz, Z = 50.
- The outputs are measured one at a time, with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Feature Description

- Wide operating voltage range.
- Operates from 1.65 V to 5.5 V.
- Allows down voltage translation.
- Inputs accept voltages to 5.5 V.
- I_{off} feature allows voltages on the inputs and outputs, when V_{CC} is 0 V.

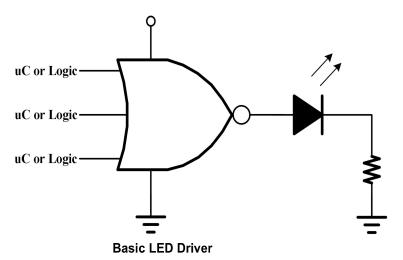
Device Functional Modes

	Output		
Α	В	С	Y
Н	X	X	L
X	Н	X	L
X	X	Н	L
L	L	L	Н



Application Information

The SN74LVC1G27DBVR-MS/SN74LVC1G27DCKR-MS is a high drive CMOS device that can be used for implement NOR logic with a high output drive, such as an LED application. It can produce 24-mA of drive current at 3.3V making it Ideal for driving multiple outputs and good for high speed applications up to 100Mhz. The inputs are 5.5-V tolerant allowing translation down to V_{CC} .

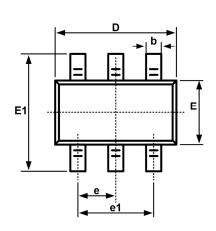


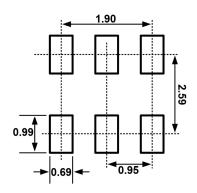
This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads, so routing and load conditions should be considered to prevent ringing.

Each VCC pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, a 0.1-µF capacitor is recommended. If there are multiple VCC pins, then a 0.01-µF or 0.022-µF capacitor is recommended for each power pin. It is ok to parallel multiple bypass capacitors to reject different frequencies of noise. A 0.1-µF and 1-µF capacitors are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

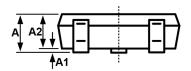


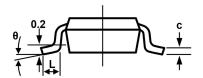
Package Outline SOT23-6





Recommended Land Pattern (Unit: mm)

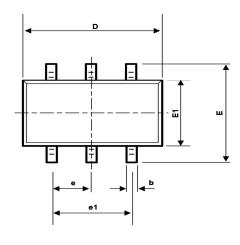


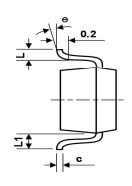


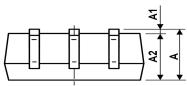
Cumb al	Dimensions I	In Millimeters	Dimension	s In Inches
Symbol	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
С	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
е	0.950	BSC	0.037	7BSC
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
L1	0.600	REF	0.024	1REF
θ	0°	8°	0°	8°



Package Outline SC70-6







Symbol	Dimension In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
Α	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
С	0.110	0.175	0.004	0.007
D	2.000	2.200	0.079	0.087
E	2.150	2.450	0.085	0.096
E1	1.150	1.350	0.045	0.053
е	0.650TYP		0.026TYP	
e1	1.200	1.400	0.047	0.055
L	0.260	0.460	0.010	0.018
L1	0.525REF		0.021REF	
θ	0°	8°	0°	8°



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